Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	9 X 9 X 0.85 (5.95 EP)
Lead Count	56
Terminal Finish	100 Sn
MS Number	MS010733B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.54E-02	86.91	869100	33.05	330519
Thermosets	Epoxy & Phenol Resin	Proprietary	1.11E-02	12.78	127800	4.86	48602
Other inorganic materials	Carbon black	1333-86-4	2.69E-04	0.31	3100	0.12	1179
Subtotal			8.67 E-02	100.00	1000000	38.03	380300

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.14 E-01	96.40	963989	49.86	498575
Copper & its alloys	Nickel	7440-02-0	2.95 E-03	2.50	25006	1.29	12933
Copper & its alloys	Silicon	7440-21-3	7.08 E-04	0.60	6004	0.31	3105
Copper & its alloys	Zinc	7440-66-6	5.90 E-04	0.50	5001	0.26	2587
Subtotal			1.18 E-01	100.00	1000000	51.72	517200

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.50 E-03	100.0	1000000	0.66	6600

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	6.04 E-03	100.0	1000000	2.65	26500

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.65 E-04	100.0	1000000	0.16	1600

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.47 E-02	100.0	1000000	6.43	64300

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Thermoset	Epoxy Resin	Proprietary	4.95 E-04	62.00	620000	0.22	2170
Other organic materials	Polytetrafluoroethylene	9002-84-0	2.71 E-04	34.00	340000	0.12	1190
Others	Curing agent	Proprietary	3.19 E-05	4.00	40000	0.01	140
Subtotal			7.98 E-04	100.0	1000000	0.35	3500

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.28 E-01**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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